

Power Dissipation (SON1612-6)

This specification is at mounted on board.

Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

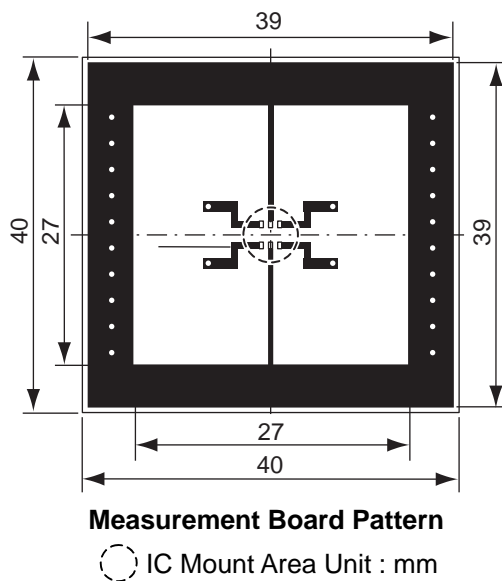
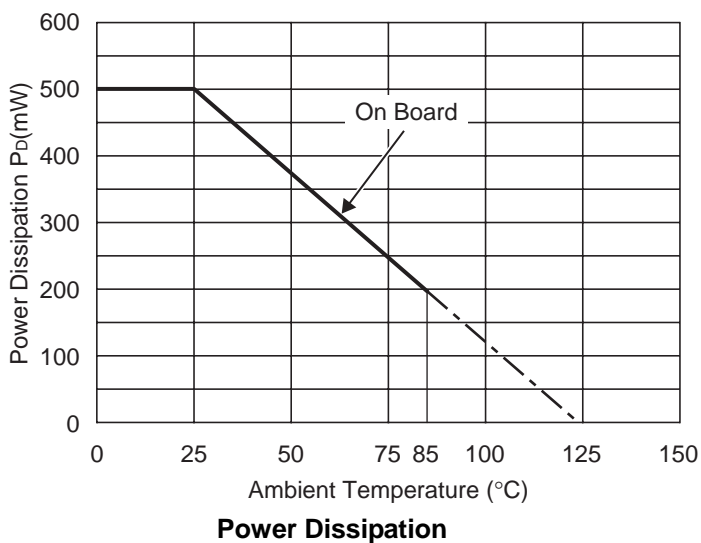
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50%, Back side : Approx.50%
Through-hole	φ0.5mm × 24pcs

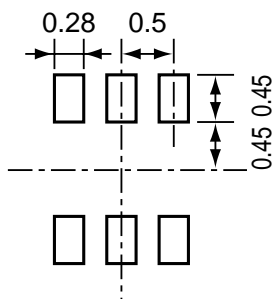
Measurement Result

($T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$)

	Standard Land Pattern
Power Dissipation	500mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/0.5W=200^{\circ}C/W$
	$\theta_{jc}=82^{\circ}C/W$



RECOMMENDED LAND PATTERN



(Unit: mm)